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Altri autori (Persone)	BaileyChristopher LiuJohan
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Nota di contenuto	Cover; Contents; Guest editorial; Coffin-Manson constant determination for a Sn-8Zn-3Bi lead-free solder joint; High strain rate testing of solder interconnections; Intermetallic compound formation and diffusion path evolution in eutectic tin-lead flip chip solder bumps after aging; Macro-micro modelling of moisture induced stresses in an ACF flip chip assembly; High performance anisotropic conductive adhesives for lead-free interconnects; Effect of curing conditions on the electrical properties of isotropic conductive adhesives composed of an epoxy-based binder Finite element analysis of fleXBGA reliabilityInternet commentary; Book review; New products; Industry news; Exhibitions and conferences; Appointments; International diary
Sommario/riassunto	This issue of Soldering & Surface Mount Technology (SSMT) presents a number of papers from the 7th High Density Microsystems Design, Packaging and Failure Analysis (HDP'05) conference held in 2005 in the dynamic city of Shanghai, China. With over 100 high quality technical papers and presentation this annual conference brings together

scholars and industrialists from Asia, Europe and the Americas to discuss the challenges and latest advances in high density packaging. This e-book contains six papers from the HDP conference, plus one additional contribution, which discuss the behaviour of key i
